

Amendments to the Specification:

Please replace the paragraph, beginning at page 5, line 27, with the following rewritten paragraph:

Surface layer 12a composed of tin or the metal which includes tin as the main substance is provided on lead conductor 12 by a hot-dip plating method or an electrical plating method. Surface layer 12a formed by the hot-dipping method has orientation of composition of metal less than surface layer 12a formed by the electrical plating method, thus having a larger wettability of metal. Alternatively, surface layer 12a may have a composition having no orientation. Lead conductor 12 can be accordingly connected to fusible alloy 11 easily and soldered to the outside object easily. The orientation of the metal composition can be reduced to a certain extent by performing a heating process after electrical plating, thus increasing the wettability. In order to have the wettability better, metal particles of surface layer 12a be preferably controlled to be not greater than 10 μ m.